



Jiangsu Yangjie Runau Semiconductor Co.,Ltd

KS350-Bidirectional thyristor

5800 - 6500 V_{DRM}

HIGH POWER BIDIRECTIONAL THYRISTOR

TS8D

Features:

- . Amplifying Gate Configuration
- . Two thyristors integrated into one wafer
- . Blocking capability up to 6500 volts
- . High power capability
- . Full cold pressing encapsulation



ELECTRICAL CHARACTERISTICS AND RATINGS

Blocking-Off State

Device No.	V _{DRM} (1)	V _{DSM} (1)
KS350/58	4900	5800
KS350/62	5300	6200
KS350/65	5600	6500

V_{DRM} = Repetitive peak off state voltage

V_{DSM} = Non Repetitive peak reverse voltage(2)

Repetitive peak reverse leakage and off state leakage	I _{DRM}	5 mA 100 mA (3)
Off - state voltage rise rating	dv/dt(4)	1000 V/μs

Notes:

All ratings are specified for T_j=25 °C unless otherwise stated.

(1) All voltage ratings are specified for an applied 50Hz/60Hz sinusoidal waveform over the temperature range-40 °C to +125 °C

(2) 10 msec. Max. Pulse width

(3) Maximum value for T_j=125 °C; 50Hz.

(4) Minimum value for linear and exponential waveshape to 67% rated V_{DRM}. Gate open, T_j=125 °C

(5) The value of di/dt is established in accordance with EIA/NIMA Standard JB/T 8950.2-2013.

Conducting-on state

Parameter	Symbol	Min.	Max.	Typ.	Units	Conditions
Average value of on-state current	I _{T(AV)}		350		A	Sinewave, 180° conduction, T _c =70°C
RMS value of on-state current	I _{TRMS}		550		A	Nominal value
Peak one cycle surge (non repetitive) current	I _{TSM}		4200		A	10.0 msec (50Hz), sinusoidal wave- shape, 180° conduction, T _j = 125 °C
I square t	I ² t		88x10 ³		A ² s	10 msec
Latching current	I _L		700		mA	V _D = 12 V; R _L = 12 ohms
Holding current	I _H		200		mA	V _D = 12 V; I = 2.5 A
Peak on-state voltage	V _{TM}		3.5		V	I _{TM} =1000A; T _j = 25°C
Threshold Voltage	V _{TO}		1.2		V	T _j =125°C
Slope resistance	r _T		2.3		mΩ	500A to 1500A
Critical rate of rise of on-state current(5)	di/dt		100		A/μs	repetition
Critical rate of rise of commutating voltage	dv/dt _{com}			500	A/μs	T _j =125°C; VR≤0.67V _{DRM}

Gating

Parameter	Symbol	Min.	Max.	Typ.	Units	Conditions
Peak gate power dissipation	P _{GM}		20		W	
Average gate power dissipation	P _{G(AV)}		4		W	
Gate trigger current	I _{GT}	50	150		mA	V _D =12V; R _L =3ohms; T _j =+25°C
Gate trigger voltage	V _{GT}	0.8	2.5		V	V _D =12V; R _L =3ohms; T _j =+25°C
Peak negative voltage	V _{GRM}		5		V	

Dynamic

Parameter	Symbol	Min.	Max.	Typ.	Units	Conditions
Delay time	t _d		3.0		μs	I _{FG} =2.0A; V _D =0.4V _{DRM} ; t _r =0.5μs
Turn-off time (V _R =-5V)	t _q			800	μs	I _{TM} =2000A; di/dt=-1.5 A/s; V _R =100 V; dV/dt=30V/μs ; V _D = 67%V _{DRM} ; T _j =125°C
Reverse recovery charge	Q _{rr}		1800		μC	I _{TM} =2000A; di/dt=-1.5 A/s; V _R =100 V; T _j =125°C

THERMAL AND MECHANICAL CHARACTERISTICS AND RATINGS

Parameter	Symbol	Min.	Max.	Typ.	Units	Conditions
Operating temperature	T _j	-40	+125		°C	
Storage temperature	T _{stg}	-40	+140		°C	
Thermal resistance- junction to case	R _{θ(j-c)}		0.045		°C/W	Double sided cooled
Thermal resistance - case to heatsink	R _{θ(c-s)}		0.008		°C/W	Double sided cooled
Mounting force	F	21	25	23	kN	
Weight	m			0.6	kg.	

* Mounting surfaces smooth, flat and greased

